Package information

1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP6

Package type industry code WLCSP6

Package style descriptive code WLCSP (wafer level chip-size package)

Mounting method type S (surface mount)

Issue date2-3-2016Manufacturer package codeSOT1454

Table 1. Package summary

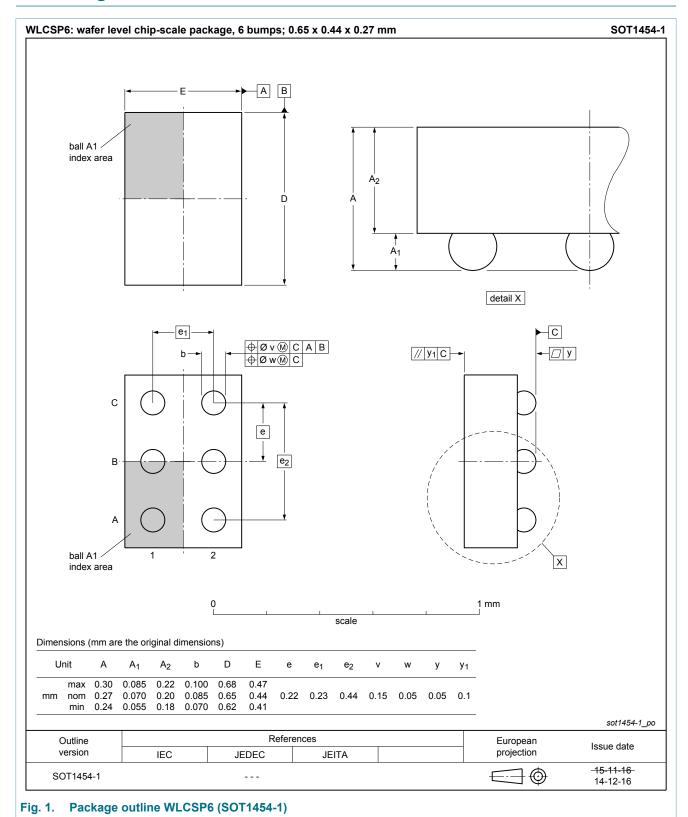
Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	0.62	-	0.65	0.68	mm
E	package width	0.41	-	0.44	0.47	mm
Α	seated height	0.24	-	0.27	0.3	mm
A ₂	package height	0.18	-	0.2	0.22	mm
е	nominal pitch	-	-	0.44	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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wafer level chip-scale package, 6 bumps

2. Package outline



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wafer level chip-scale package, 6 bumps

3. Legal information

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wafer level chip-scale package, 6 bumps

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